



Material Content Data Sheet



Sales Product Name		BSC0909NS		Issued		24. January 2018		
MA#		MA001251526						
Package		PG-TDSON-8-14		Weight*		104.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.614	0.59	0.59	5880	5880
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		93	
	non noble metal	zinc	7440-66-6	0.039	0.04		373	
	non noble metal	iron	7439-89-6	0.778	0.75		7453	
wire	non noble metal	copper	7440-50-8	31.590	30.26	31.06	302635	310554
	non noble metal	copper	7440-50-8	0.054	0.05	0.05	517	517
encapsulation	organic material	carbon black	1333-86-4	0.261	0.25		2497	
	plastics	epoxy resin	-	8.079	7.74		77397	
	inorganic material	silicondioxide	60676-86-0	43.783	41.94	49.93	419444	499338
leadfinish	non noble metal	tin	7440-31-5	1.243	1.19	1.19	11904	11904
plating	noble metal	silver	7440-22-4	0.037	0.04	0.04	359	359
solder	noble metal	silver	7440-22-4	0.024	0.02		234	
	non noble metal	tin	7440-31-5	0.020	0.02		187	
	non noble metal	lead	7439-92-1	0.932	0.89	0.93	8928	9349
heat sink CLIP	non noble metal	iron	7439-89-6	0.017	0.02		162	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		49	
	non noble metal	copper	7440-50-8	16.898	16.19	16.21	161888	162099
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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